

# EPO-TEK® 353NDP

# High Temperature Humidity Resistant Epoxy

Preliminary Product Information Sheet

Date: May 2025

Rev:

No. of Components: Two Mix Ratio by Weight: 10:1

Specific Gravity: Bulk - Part A: 1:20, Part B: 1.02

Syringe: 1.18

Pot Life: Bulk: ≤3 Hours, Syringe: ≤2 Hours

Shelf Life- Bulk: One year at room temperature

Shelf Life- Syringe: Six months at -40°C Recommended Cure: 120°C / 1 Hour Alternative Cure(s): May not achieve

performance properties below

150°C / 1 Hour

#### **Product Description:**

EPO-TEK\* 353NDP is a two component, high temperature and high humidity resistance epoxy designed for optical, telecom, datacom, HI-REL microelectronics, semiconductor and hybrid applications. Also available in single component frozen syringe.

## **Typical Properties:**

Cure condition: 120°C / 1 Hour

Different batches, conditions, and applications yield differing results.

Data contained herein is preliminary and subject to change without notice. To be used as guide only, not as a specification.

#### **Notes:**

- Container(s) should be kept closed when not in use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- If product crystalizes in storage, place container in warm oven until crystallization disappears. Please refer to Tech Tip #7 on website.
- TOTAL MASS MIXED SHOULD NOT EXCEED 25 GRAMS

Physical Properties	Details	
* Color (before cure)	Part A: Clear, Part B: Amber	
* Consistency	Pourable liquid	
* Viscosity (23°C) @ 50 rpm	3,000 - 5,000 cPs	
Thixotropic Index	N/A	
* Glass Transition Temp	≥ 90°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE)	Pending	
Shore D Hardness	85	
Lap Shear @ 23°C	Pending	
Die Shear @ 23°C	38 Kg; 32 Kg (after 7d @ 85°C / 85% RH); 15 Kg (after 2000h @ 85°C / 85% RH)	
Degradation Temp	410°C	
Weight Loss:	@ 200°C: 0.09%, @ 250°C: 0.28%, @ 300°C: 0.72%	
Suggested Operating Temperature	< 350°C (Intermittent)	
Storage Modulus:	Pending	
Ion Content	Pending	
*Particle Size	N/A	

<sup>\*</sup>denotes test on lot acceptance basis.



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Electrical & Thermal Properties	Details
Thermal Conductivity	N/A
Volume Resistivity @ 23°C	≥ 1.8 x 10 <sup>13</sup> Ohm-cm
Dielectric Constant (1KHz)	3.17
Dissipation Factor (1KHz)	0.005

Optical Properties @23°C	Details
Spectral Transmission:	≥ 50% @ 550 nm
	≥ 95% @ 1100-1600 nm
	≥ 98% @ 800-1000 nm
Refractive Index:	1.569 @589 nm

### **EPO-TEK® 353NDP Advantages & Suggested Application Notes**

- Reasonable pot-life that allows for low temperature curing to be realized. It has an amber color change upon cure.
- Semiconductor suggested applications: wafer-wafer bonding of CSP; fabrication of MEMs devices; flip chip underfill.
- Hybrid suggested applications: providing near hermetic seals and UHV seals in sensor devices, resisting high temperature packaging.
  - o Down-Hole petrochemical fiber optic sensors, resisting >200°C field conditions.
  - o HI-REL microelectronics assembly for automotive electronics, autonomous, aviation, and defense
- Suggested optical, telecom, and datacom applications:
  - o Sealing fiber into ferrules, transmitting light in the optical pathway from 800-1550 nm range.
  - o High speed data transceiver device adhesive for active alignment of optics, environmental sealing of opto-package, V-groove arrays.
- Electronics Assembly suggested applications:
  - o Used as dielectric layer in the fabrication of capacitors; laminating PZT ferroelectrics found in ultrasound or ink-jetting devices.
  - o Impregnating and insulating copper coil windings in motors and inductor coils. Bonding ferrite cores and magnets.
  - o Structural grade epoxy for bonding of SST metals, Kapton®, and magnets.



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